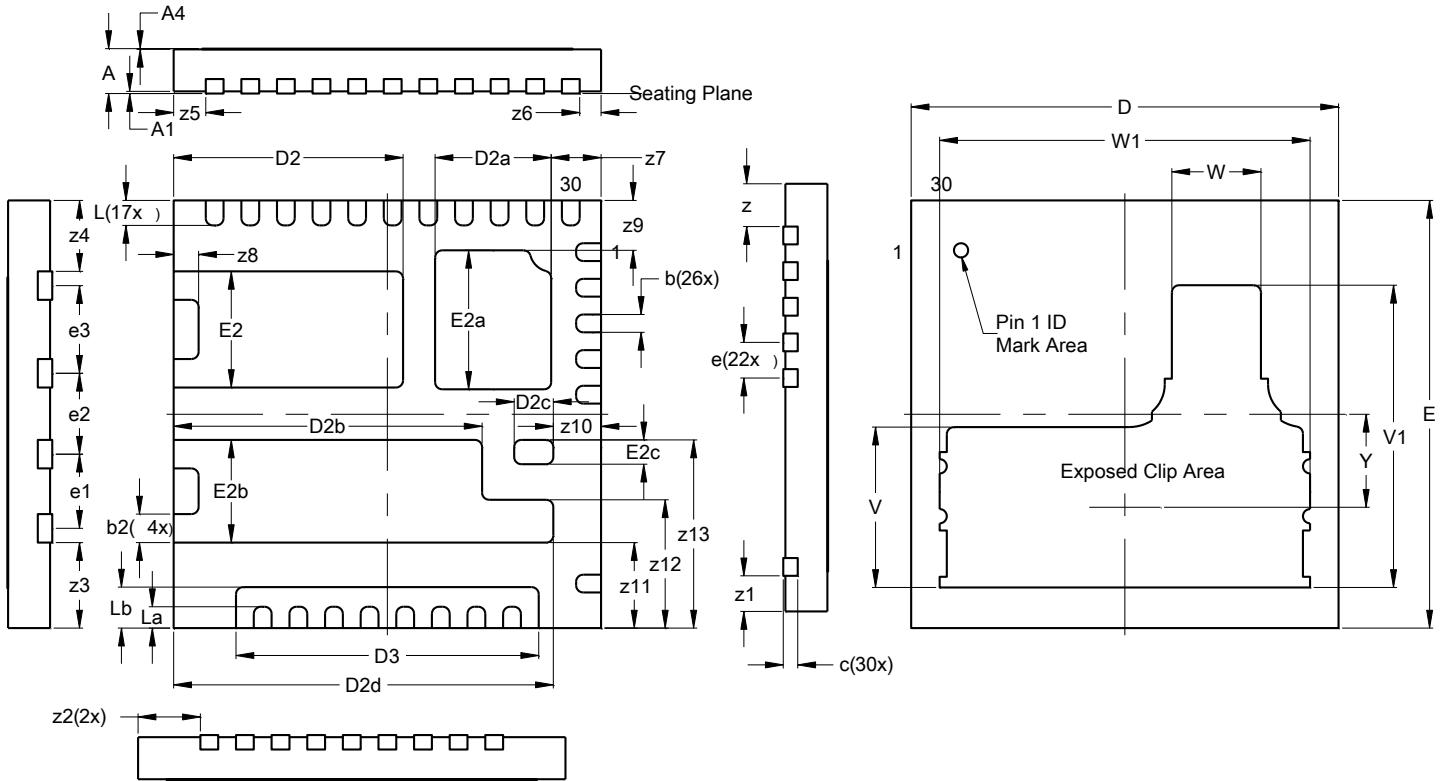


Package Outline Dimensions

W-QFN6060-30 (Type A)



W-QFN6060-30 (Type A)											
Dim	Min	Max	Typ	Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.55	0.75	0.65	D2c	0.290	0.390	0.340	Z4	0.995 BSC		
A1	0.00	0.050	0.020	e	0.500 BSC			Z5	0.450 BSC		
A4	0.00	0.050	0.020	e1	1.040 BSC			Z6	0.300 BSC		
b	0.20	0.30	0.25	e2	1.135 BSC			Z7	0.650	0.750	0.700
b2	0.350	0.450	0.400	e3	1.230 BSC			Z8	0.300	0.400	0.350
c	0.203 REF			L	0.300	0.400	0.350	Z9	0.650	0.750	0.700
D	0.600 BSC			La	0.250	0.350	0.300	Z10	0.620	0.720	0.670
D2	3.170	3.270	3.220	Lb	0.525	0.625	0.575	Z11	1.150	1.250	1.200
D2a	1.580	1.680	1.630	V	2.150	2.350	2.250	Z12	1.750	1.850	1.800
D2b	4.280	4.380	4.330	V1	4.140	4.340	4.240	Z13			
D2c	0.500	0.600	0.550	W	1.150	1.350	1.250				
D2d	5.280	5.380	5.330	W1	5.100	5.300	5.200				
D3	4.200	4.300	4.250	Y	1.205	1.405	1.305				
E	0.600 BSC			z	0.600 BSC						
E2	1.580	1.680	1.630	z1	0.500 BSC						
E2a	1.900	2.00	1.950	z2	0.875 BSC						
E2b	1.390	1.490	1.440	z3	1.200 BSC						

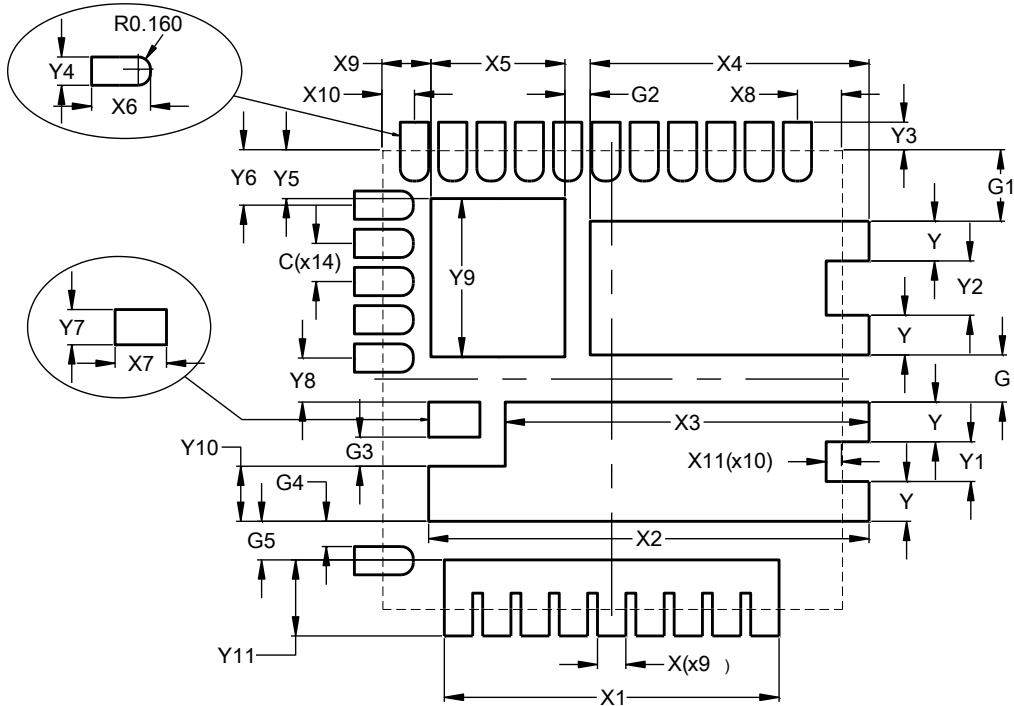
All Dimensions in mm

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Suggested Pad Layout

W-QFN6060-30 (Type A)



Dimensions	Value (in mm)	Dimensions	Value (in mm)	Dimensions	Value (in mm)
C	0.500	X5	1.750	Y5	0.640
G	0.615	X6	0.770	Y6	0.725
G1	0.935	X7	0.670	Y7	0.460
G2	0.330	X8	0.575	Y8	0.575
G3	0.380	X9	0.640	Y9	2.070
G4	0.330	X10	0.425	Y10	0.720
G5	0.505	X11	0.200	Y11	0.995
X	0.370	Y	0.520		
X1	4.370	Y1	0.520		
X2	5.750	Y2	0.710		
X3	4.750	Y3	0.360		
X4	3.640	Y4	0.370		

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.